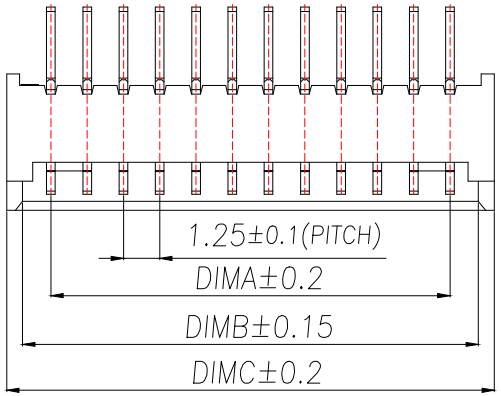
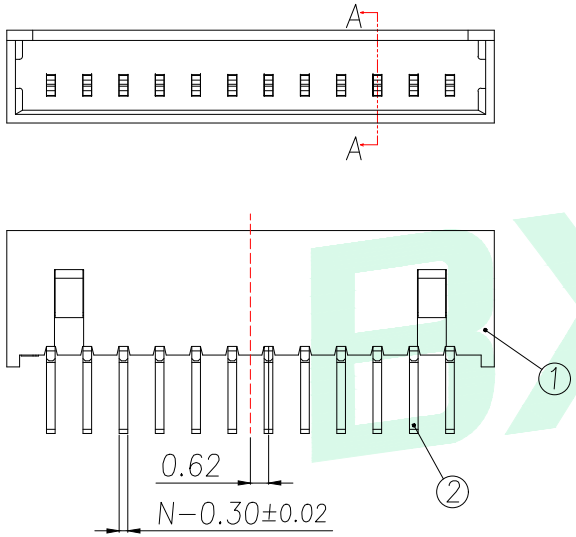
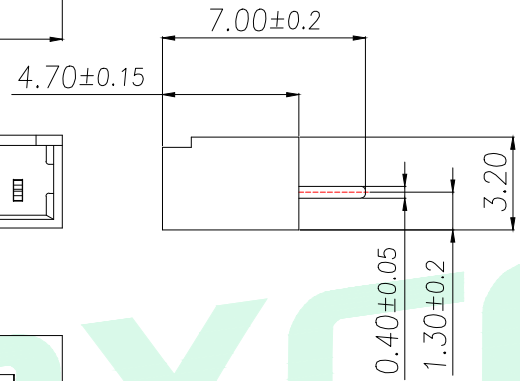
REV.	DESCRIPTION	ECN NO.	NAME	DATE

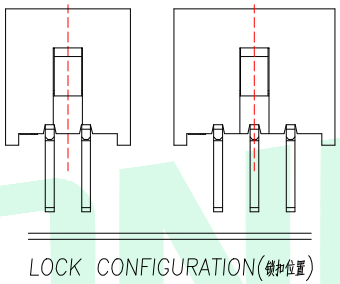


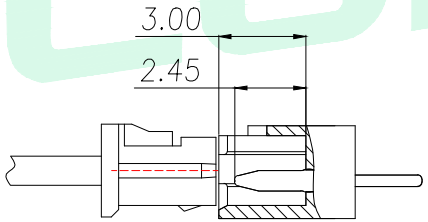
序号	品名	材质
1	1.25 Pitch S/T Wire To Board Housing DIP(H=4.7)	PA66 UL94V-2 Yellow
2	1.25 Pitch S/T Wire To Board Terminal DIP(H=4.7)	Copper Alloy/ Tin Plating

Part No	Pin	A	B	C
AF-MX1.25-2PZZ-H2	2	1.25	3.20	4.30
AF-MX1.25-3PZZ-H2	3	2.50	4.45	5.55
AF-MX1.25-4PZZ-H2	4	3.75	5.70	6.80
AF-MX1.25-5PZZ-H2	5	5.00	6.95	8.05
AF-MX1.25-6PZZ-H2	6	6.25	8.20	9.30
AF-MX1.25-7PZZ-H2	7	7.50	9.45	10.55
AF-MX1.25-8PZZ-H2	8	8.75	10.70	11.80
AF-MX1.25-9PZZ-H2	9	10.00	11.95	13.05
AF-MX1.25-10PZZ-H2	10	11.25	13.20	14.30
AF-MX1.25-11PZZ-H2	11	12.50	14.45	15.55
AF-MX1.25-12PZZ-H2	12	13.75	15.70	16.80
AF-MX1.25-13PZZ-H2	13	15.00	16.95	18.05
AF-MX1.25-14PZZ-H2	14	16.25	18.20	19.30
AF-MX1.25-15PZZ-H2	15	17.50	19.45	20.55
AF-MX1.25-16PZZ-H2	16	18.75	20.70	21.80
AF-MX1.25-17PZZ-H2	17	20.00	21.95	23.05
AF-MX1.25-18PZZ-H2	18	21.25	23.20	24.30
AF-MX1.25-19PZZ-H2	19	22.50	24.45	25.55
AF-MX1.25-20PZZ-H2	20	23.75	25.70	26.80

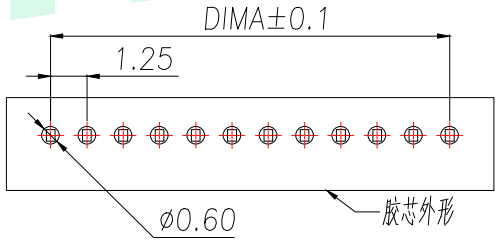








SECTION A-A



适用线路板(PCB LAYOUT)

Technical Index:

1.The surface of the plastic parts should be smooth,no rough edges,no obvious shrinkage,defects,cracks and other phenomena)

2.Lock Configuration:2 to 3Pin is 1,≥4Pin is 2

3.Temperature range:-40°C~+85°C.

4.Rated voltage:125V,AC/DC.

5.Contact resistance:≤0.02Ω.

6.Insulation resistance:≥100MΩ

GENERAL TOLERANCE					DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD		BXCONN®
DIM.	TOL.				TITLE: 1.25 PITCH H4.7 S/T WIRE TO BOARD DIP CONN.		
x.	±0.50						
x.x	±0.20						
x.xx	±0.10						
GENERAL	ANGLE:				DWG. NO.: AF-MX1.25-NPZZ-H2	CHECKED: MAX	
x.°	±5°						
x.x°	±3°						
x.xx°	±1°				PART NO.: AF-MX1.25-NPZZ-H2	DRAWN: ELLA	
		UNIT: mm	SCALE: none	SHEET: 1of 1	DWG. SIZE: A4 / LAYER: bxconn	APPROVED: WILL	